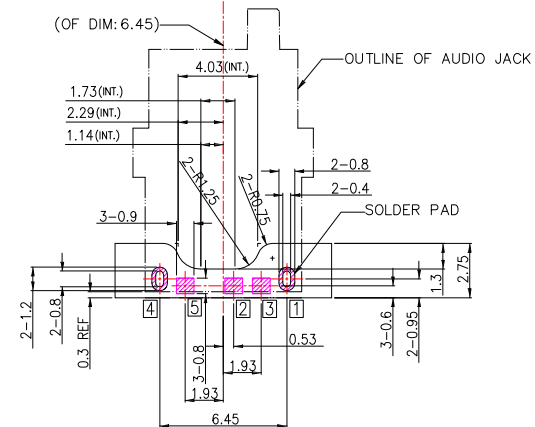
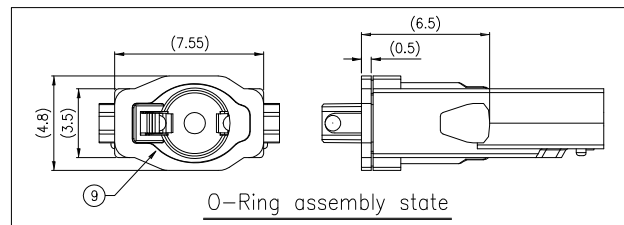
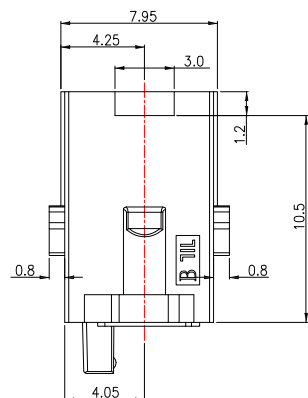
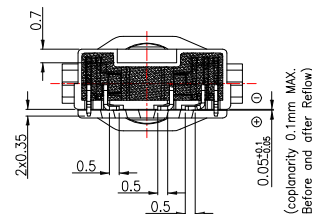
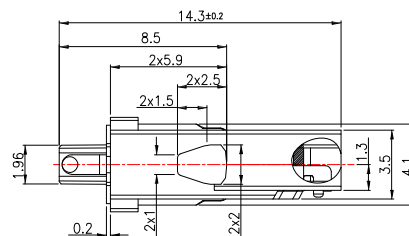
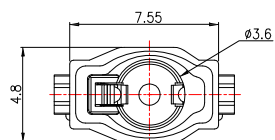


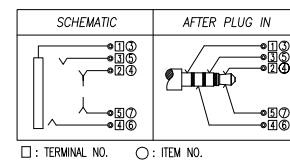
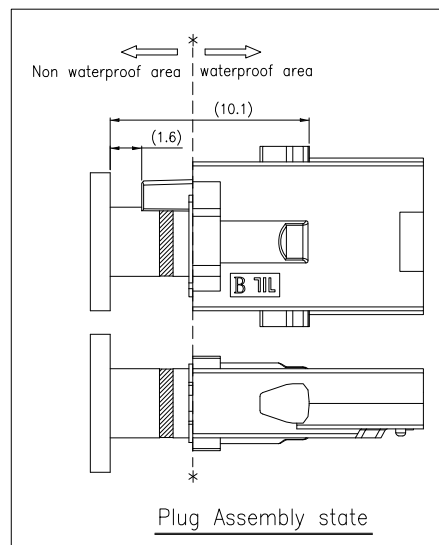
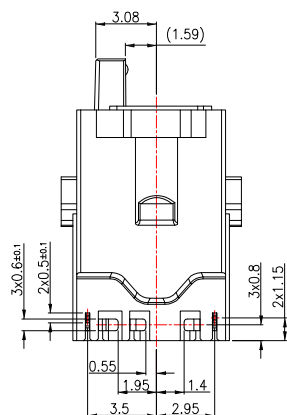


PCB Layout
(Top view)



SPECIFICATION

1. Contact resistance : $\leq 30m\Omega$
2. Insulation resistance : $\geq 500M\Omega$
3. Withstand voltage : 500VAC
5. Insertion and extraction force : 4~25N
6. Life test : 5,000 cycles
7. Waterproof Level: IPx8



⑨	O-RING	----	1	----	----
⑧	BOND	----	1	----	----
⑦	TIP SPRING-2	⑤	1	SUS	
⑥	RING SPRING-2	④	1	C5210	Under plating: Ni plating; Contact area: Au plating Soldering area: Au plating
⑤	RING SPRING-1	③	1	C5210	Under plating: Ni plating; Contact area: Au plating Soldering area: Au plating
④	TIP SPRING-1	②	1	SUS	Under plating: Ni plating; Contact area: Au plating Soldering area: Au plating
③	EARTH SPRING	①	1	C5210	Under plating: Ni plating; Contact area: Au plating Soldering area: Au plating
②	COVER	----	1	PA9T(BLACK)	
①	HOUSING	----	1	PA9T(BLACK)	
ITFM	PART	NAMF	TFRMIAL	QTY	RFMARK

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S

UNITS MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 01/26/24
DATE: 01/26/24
DATE: 01/26/24

MAT'L		TITLE	JACK
FINISH		MODLE	3.5mm PHONE JACK 防水型
SCALE	1 : 1	DWG NO.	PJ-WP3035-S404
SHEET NO.	1 of 1	PART NO.	PJ-WP3035-S404

SIZE	A4
VER	R